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Quad. 2-to-1-line Data Selectors/Multiplexers (with noninverted outputs) Quad. 2-to-1-line Data Selectors/Multiplexers (with inverted outputs)



ADE-205-454 (Z) 1st. Edition Sep. 2000

Description

These devices each consist of four 2-input digital multiplexers with common select and strobe inputs. On the HD74HC157, when the strobe input is at logical "L" the four outputs assume the values as selected from the inputs. When the strobe input is at a logical "H" the outputs assume logical "L". The HD74HC158 operates in the same manner, except that its outputs are inverted. Select decoding is done internally resulting in a single select input only. If enabled, the select input determines whether the A or B inputs get routed to their corresponding Y outputs.

Features

• High Speed Operation: t_{pd} (Data to Output) = 12 ns typ ($C_L = 50 \text{ pF}$)

• High Output Current: Fanout of 10 LSTTL Loads

• Wide Operating Voltage: $V_{CC} = 2$ to 6 V

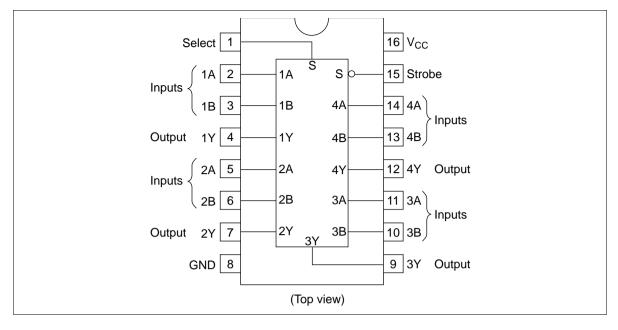
• Low Input Current: 1 μA max

• Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max (Ta = 25°C)

Function Table

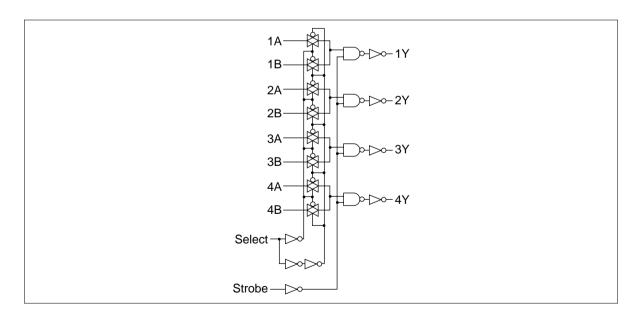
Inputs			Output Y			
Strobe	Select	Α	В	HC157	HC158	
Н	Х	Х	Х	L	Н	
L	L	L	Χ	L	Н	
L	L	Н	Χ	Н	L	
L	Н	Х	L	L	Н	
L	Н	Х	Н	Н	L	

Pin Arrangement

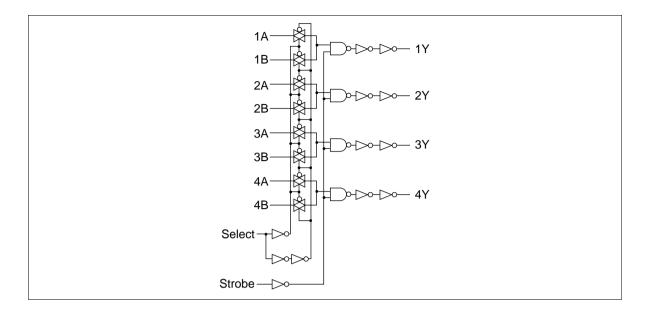


Logic Diagram

HD74HC157



HD74HC158



DC Characteristics

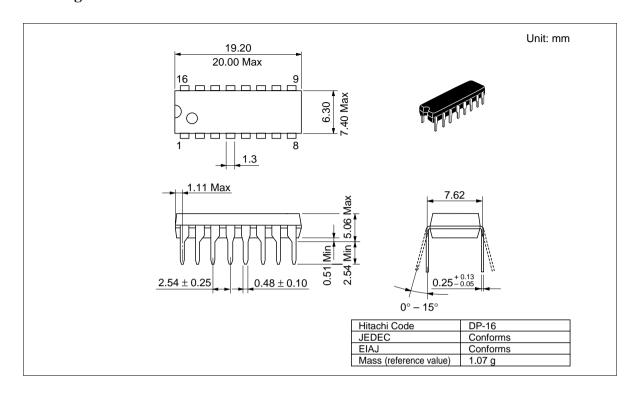
			Ta = 25°C		Ta = -40 to +85°C					
Item	Symbol	V _{cc} (V)	Min	Тур	Max	Min	Max	Unit	Test Condition	ns
Input voltage	V _{IH}	2.0	1.5		_	1.5	_	V		
		4.5	3.15	_	_	3.15				
		6.0	4.2	_	_	4.2	_	_		
	V _{IL}	2.0	_	_	0.5	_	0.5	V		
		4.5	_	_	1.35	_	1.35			
		6.0	_	_	1.8	_	1.8			
Output voltage	V _{OH}	2.0	1.9	2.0	_	1.9	_	V	$Vin = V_{IH} \text{ or } V_{IL}$	$I_{OH} = -20 \mu A$
		4.5	4.4	4.5	_	4.4	_			
		6.0	5.9	6.0	_	5.9	_	_		
		4.5	4.18	_	_	4.13	_			$I_{OH} = -4 \text{ mA}$
		6.0	5.68	_	_	5.63	_	_		$I_{OH} = -5.2 \text{ mA}$
	V _{OL}	2.0	_	0.0	0.1	_	0.1	V	$Vin = V_{IH} \text{ or } V_{IL}$	I _{OL} = 20 μA
		4.5	_	0.0	0.1	_	0.1			
		6.0	_	0.0	0.1	_	0.1	_		
		4.5	_	_	0.26	_	0.33			I _{OL} = 4 mA
		6.0	_	_	0.26	_	0.33	_		I _{OL} = 5.2 mA
Input current	lin	6.0	_	_	±0.1	_	±1.0	μΑ	Vin = V _{CC} or Gi	ND
Quiescent supply current	I _{cc}	6.0	_	_	4.0	_	40	μΑ	Vin = V _{CC} or Gi	ND, lout = $0 \mu A$

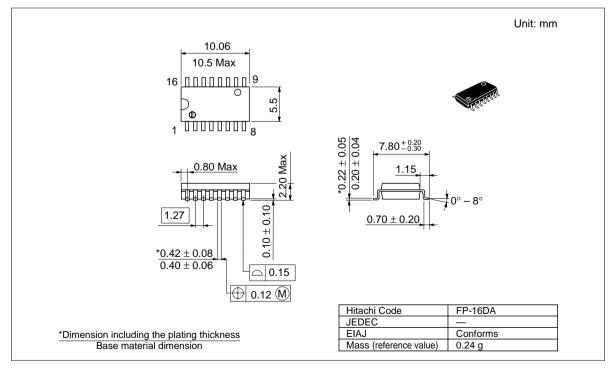
AC Characteristics ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$)

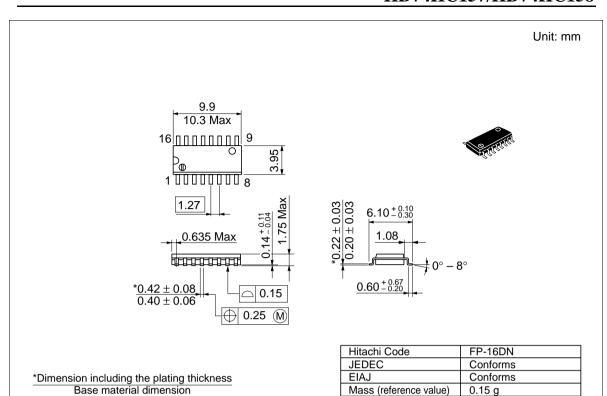
Ta = -40 to Ta = 25°C +85°C

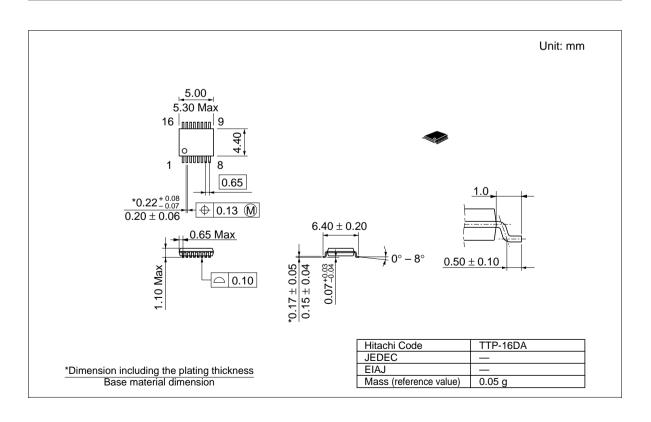
Item	Symbol	V _{cc} (V)	Min	Тур	Max	Min	Max	Unit	Test Conditions	
Propagation delay	t _{PLH}	2.0	_	_	125	_	155	ns	Data to	HD74HC157 only
time	$t_{\tiny PHL}$	4.5	_	12	25	_	31	_	output	
		6.0	_	_	21	_	26			
	t _{PLH}	2.0	_	_	110		140	ns	_	HD74HC158 only
	$t_{\tiny PHL}$	4.5	_	12	22	_	28	_		
		6.0	_	_	19	_	24			
	t _{PHL}	2.0	_	_	125	_	155	ns	Select to output	
		4.5	_	13	25	_	31	_		
		6.0	_	_	21	_	26			
	t _{PLH}	2.0	_	_	160	_	200	ns	_	
		4.5	_	17	32	_	40			
		6.0	_	_	27	_	34			
	t _{PHL}	2.0	_	_	160	_	200	ns	Strobe to o	output
		4.5	_	12	32	_	40	_		
		6.0	_	_	27	_	34			
	t _{PLH}	2.0	_	_	160	_	200	ns	_	
		4.5	_	12	32	_	40	_		
		6.0		_	27	_	34			
Output rise/fall	t _{TLH}	2.0	_	_	75	_	95	ns		
time	$t_{\scriptscriptstyle THL}$	4.5	_	5	15	_	19	-		
		6.0	_	_	13	_	16	=		
Input capacitance	Cin	_	_	5	10	_	10	pF		

Package Dimensions









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